

## General Description

The MY40N03BNE3 is the highest performance trench N-CH MOSFETS with extreme high cell density, which provide excellent  $R_{DS(on)}$  and gate charge for most of the small power switching and load switch applications.

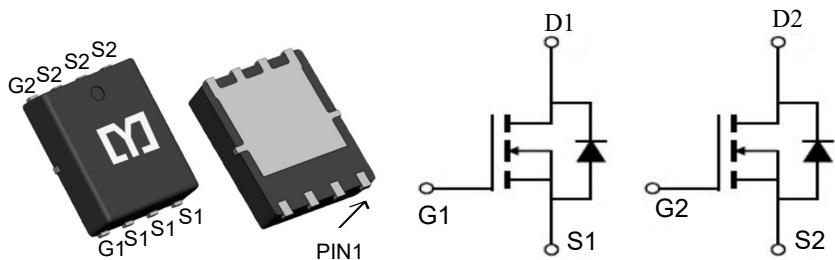


## Features

$V_{DSS}$	30	V
$I_D$	40	A
$R_{DS(ON)}(\text{at } V_{GS}=10\text{V})$	6	$\text{m}\Omega$
$R_{DS(ON)}(\text{at } V_{GS}=4.5\text{V})$	8	$\text{m}\Omega$

## Application

- Battery protection
- Load switch
- Uninterruptible power supply



## Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
MY40N03BNE3	PDFN3*3-8	NULL	5000

## Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	30	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_C=25^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10\text{V}^1$	40	A
$I_D @ T_C=100^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10\text{V}^1$	30	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	120	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	39	mJ
$I_{AS}$	Avalanche Current	50	A
$P_D @ T_C=25^\circ\text{C}$	Total Power Dissipation <sup>4</sup>	18	W
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

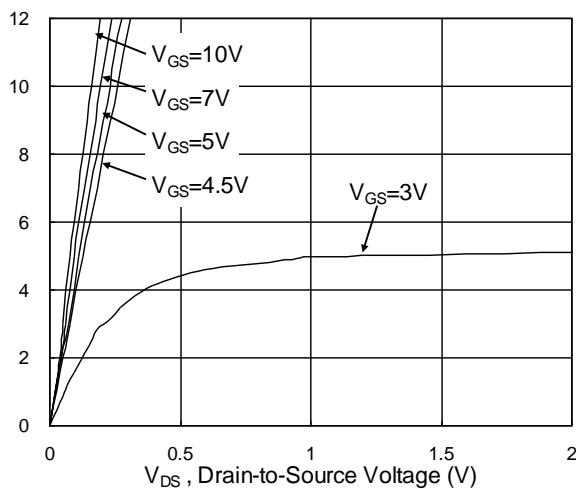
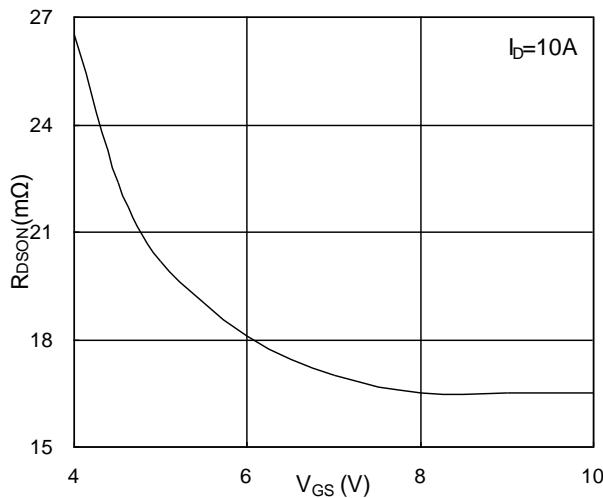
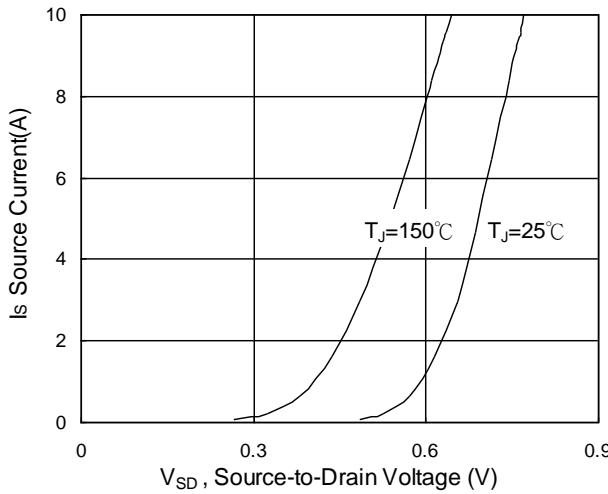
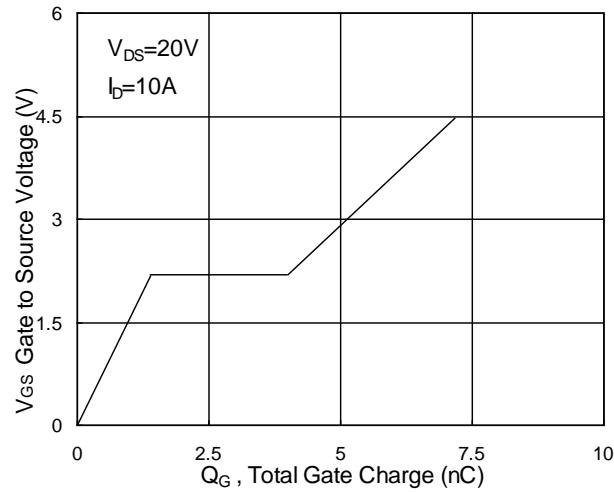
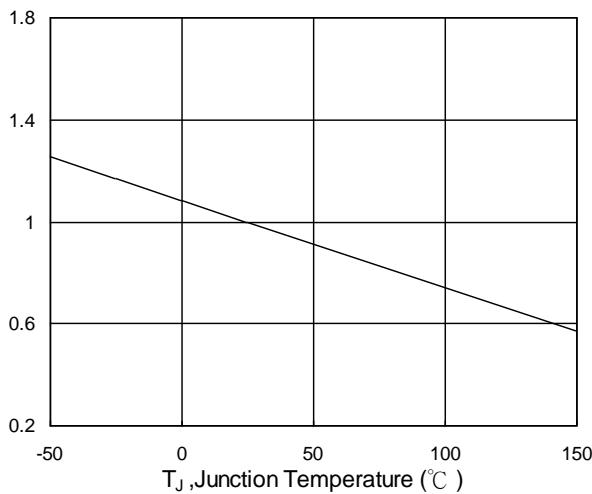
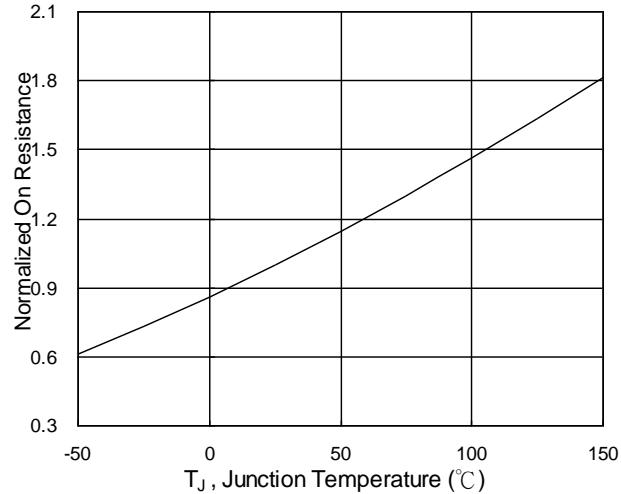
Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	30	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	BVDSS Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$	---	0.023	---	$\text{V}/^\circ\text{C}$
$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=10\text{V}$ , $I_D=15\text{A}$	---	6	8	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$ , $I_D=10\text{A}$	---	8	11	
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D=250\mu\text{A}$	1.0	---	2.5	V
$\Delta V_{\text{GS}(\text{th})}$	$V_{\text{GS}(\text{th})}$ Temperature Coefficient		---	-5.08	---	$\text{mV}/^\circ\text{C}$
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=24\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\text{uA}$
		$V_{\text{DS}}=24\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=55^\circ\text{C}$	---	---	5	
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=5\text{V}$ , $I_D=15\text{A}$	---	24.4	---	S
$R_g$	Gate Resistance	$V_{\text{DS}}=0\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	1.8	---	$\Omega$
$Q_g$	Total Gate Charge (4.5V)	$V_{\text{DS}}=15\text{V}$ , $V_{\text{GS}}=4.5\text{V}$ , $I_D=12\text{A}$	---	9.82	---	nC
$Q_{\text{gs}}$	Gate-Source Charge		---	2.24	---	
$Q_{\text{gd}}$	Gate-Drain Charge		---	5.54	---	
$T_{\text{d}(\text{on})}$	Turn-On Delay Time	$V_{\text{DD}}=15\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $R_{\text{G}}=1.5\text{ }\Omega$ $I_D=20\text{A}$	---	6.4	---	ns
$T_r$	Rise Time		---	39	---	
$T_{\text{d}(\text{off})}$	Turn-Off Delay Time		---	21	---	
$T_f$	Fall Time		---	4.7	---	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=15\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	896	---	pF
$C_{\text{oss}}$	Output Capacitance		---	126	---	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	108	---	
$I_s$	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	37	A
$I_{\text{SM}}$	Pulsed Source Current <sup>2,5</sup>		---	---	75	A
$V_{\text{SD}}$	Diode Forward Voltage <sup>2</sup>	$V_{\text{GS}}=0\text{V}$ , $I_s=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1	V

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}=25\text{V}$ ,  $V_{\text{GS}}=10\text{V}$ ,  $L=0.1\text{mH}$ ,  $I_{\text{AS}}=21\text{A}$
- 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5.The data is theoretically the same as  $I_D$  and  $I_{\text{DM}}$  , in real applications , should be limited by total power dissipation.

### Typical Characteristics

**Fig.1 Typical Output Characteristics****Fig.2 On-Resistance vs. Gate-Source****Fig.3 Forward Characteristics Of Reverse****Fig.4 Gate-Charge Characteristics****Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$** **Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$**

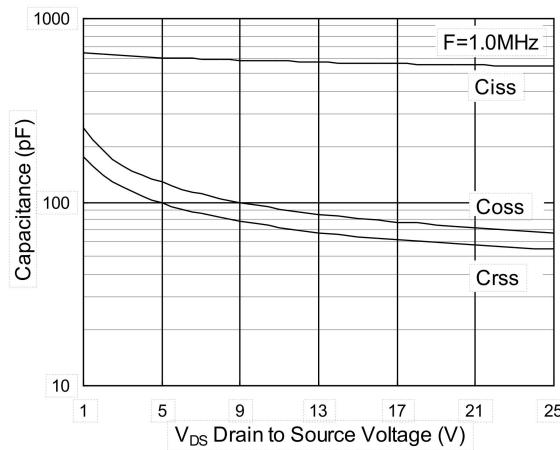


Fig.7 Capacitance

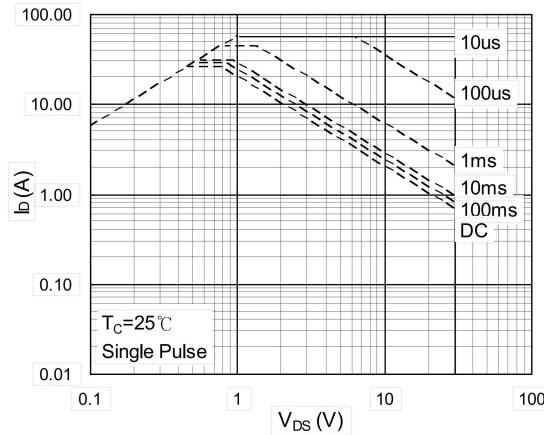


Fig.8 Safe Operating Area

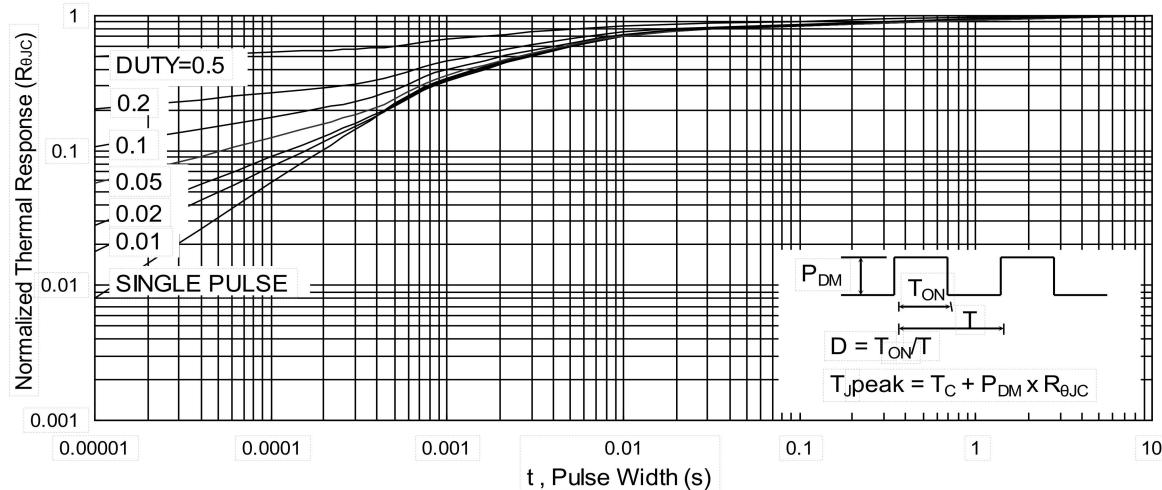


Fig.9 Normalized Maximum Transient Thermal Impedance

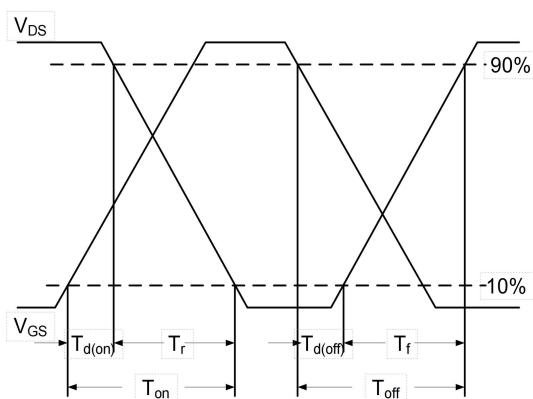


Fig.10 Switching Time Waveform

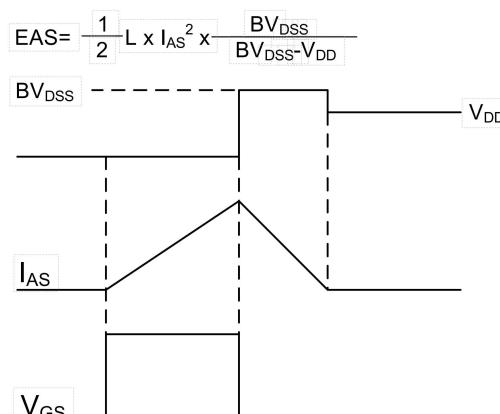
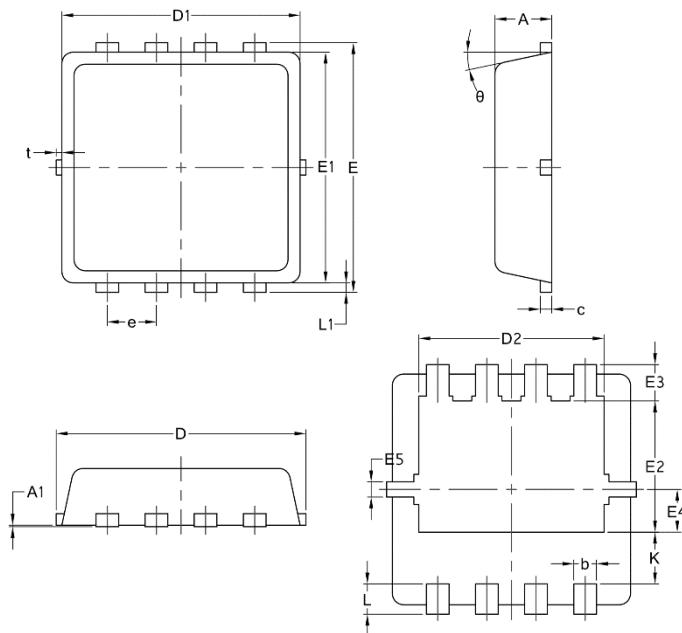


Fig.11 Unclamped Inductive Switching Waveform

## Package Mechanical Data-DFN3\*3-8L-JQ Single



Symbol	Common		
	mm		
	Mim	Nom	Max
A	0.70	0.75	0.85
A1	/	/	0.05
b	0.20	0.30	0.40
c	0.10	0.152	0.25
D	3.15	3.30	3.45
D1	3.00	3.15	3.25
D2	2.29	2.45	2.65
E	3.15	3.30	3.45
E1	2.90	3.05	3.20
E2	1.54	1.74	1.94
E3	0.28	0.48	0.65
E4	0.37	0.57	0.77
E5	0.10	0.20	0.30
e	0.60	0.65	0.70
K	0.59	0.69	0.89
L	0.30	0.40	0.50
L1	0.06	0.125	0.20
t	0	0.075	0.13
$\Phi$	10	12	14